



# INFORMATION DISCLOSURE STATEMENT

SHEET 1 OF 1

Complete it known

**Application Number: 10/076,858**

**Filing Date: February 14, 2002**

Group A8 Unit: 1335

Examiner Name: Stephen J. Stein

Attorney Docket Number: R&H 03-19

## UNITED STATES PATENT DOCUMENTS

EXAMINER'S INITIALS	CITE NO.	PATENT NUMBER	ISSUE DATE MM-DD-YYYY	FIRST NAMED INVENTOR
		4810557	03/07/1989	Blender
		4837429	06/06/1989	Pfisch et al.
		4863560	09/06/1989	Hawkins
		4904036	02/27/1990	Blender
		4938841	07/03/1990	Shahar et al.
		4957502	09/18/1990	O'Neill
		5338400	08/16/1994	Jerman
		5478438	12/26/1995	Nakanishi et al.
		5479426	12/26/1995	Nakanishi et al.
		5614106	03/11/1997	Tabuchi
		5911021	06/08/1999	MacDonald et al.
		6132107	10/17/2000	Morikawa
		6187515	02/13/2001	Tran et al.
		6257772	07/10/2001	Nakanishi et al.
		6559173	04/22/2003	Goto
		6567590	05/20/2003	Okada et al.
		US 2002/0105417	12/26/2002	Steinberg
		US 2003/0020130	01/30/2003	Steinberg et al.
SSS		US 2003/0067049	04/10/2003	Steinberg et al.
		US 2003/0021572	01/30/2003	Steinberg

## FOREIGN PATENT DOCUMENTS

EXAMINER'S INITIALS	CITE NO.	DOCUMENT NUMBER	COUNTRY OR REGION	DATE OF PUBLICATION MM-DD-YYYY	FIRST NAMED INVENTOR OR APPLICANT

## OTHER PRIOR ART - NON-PATENT DOCUMENTS

EXAMINER'S INITIALS	CITE NO.	Include name of the author (in Capital Letters), title of the article (when appropriate), title of the item(book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published
		Nijdam, et al. "Etching of silicon in alkaline solutions: a critical look at the (111) minimum," MESA
		Costerbroek, et al. "New design methodologies in <111> oriented silicon wafers," MESA
		Suchtelen, et al. "Simulation of Anisotropic Wet Chemical Etching Using a Physical Model," MESA

**EXAMINER'S  
SIGNATURE**

Stephen Stein

**DATE  
CONSIDERED**

6/12/2005

**EXAMINER:** Initial if reference considered, whether or not citation is in conformance with MPEP § 609. Draw a line through citation if citation not in conformance and reference not considered. Include a copy of this form with next communication to applicant.